

Electronic Patent Application Fee Transmittal

Application Number:	09590897			
Filing Date:	09-Jun-2000			
Title of Invention:	Sealing structure for multi-chip module			
First Named Inventor/Applicant Name:	Kouichi Takahashi			
Filer:	George B. F. Yee			
Attorney Docket Number:	16869P010700US			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120